

### Features

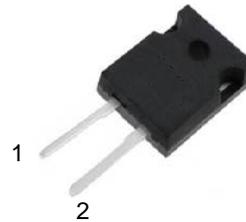
- Low reverse current
- Good surge current capability
- Low capacitive charge
- No reverse recovery current
- Halogen free, RoHs compliant

$V_{RRM}$	=	1700 V
$I_F (T_C=164^\circ\text{C})$	=	10 A
$Q_C$	=	114 nC

### Benefits

- System efficiency improvement over Si diodes
- Higher switching frequency
- Increased power density
- Essentially no switching losses

### Package



TO-247-2



### Applications

- Switch mode power supplies (SMPS)
- Uninterruptible power supplies
- On Board Charger
- UPS

Part Number	Package	Marking
ASZD010170C	TO-247-2	ASZD010170C

**Maximum Ratings( $T_C = 25^\circ\text{C}$ , unless other wise specified)**

Symbol	Parameter	Test conditions	Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage		1700	V
$V_{RSM}$	Non-repetitive peak reverse voltage		1700	V
$I_F$	Continuous forward current	$T_C=25^\circ\text{C}$ $T_C=135^\circ\text{C}$ $T_C=165^\circ\text{C}$	51 24 10	A
$I_{FRM}$	Repetitive forward surge current	$T_C=25^\circ\text{C}$ , $t_p=10\text{ms}$ , Half Sine Pulse $T_C=110^\circ\text{C}$ , $t_p=10\text{ms}$ , Half Sine Pulse	45 25	A
$I_{FSM}$	Non-Repetitive forward surge current	$T_C=25^\circ\text{C}$ , $t_p=10\text{ms}$ , Half Sine Pulse $T_C=110^\circ\text{C}$ , $t_p=10\text{ms}$ , Half Sine Pulse	105 90	A
$\int i^2 dt$	$i^2t$ value	$T_C=25^\circ\text{C}$ , $t_p=10\text{ms}$ , Half Sine Pulse $T_C=110^\circ\text{C}$ , $t_p=10\text{ms}$ , Half Sine Pulse	55 24	A <sup>2</sup> S
$P_{tot}$	Power dissipation	$T_C=25^\circ\text{C}$ $T_C=110^\circ\text{C}$	242 105	W
$T_j$	Operating junction temperature		-55~175	$^\circ\text{C}$
$T_{stg}$	Storage temperature		-55~175	$^\circ\text{C}$

**Electrical Characteristics( $T_j = 25^\circ\text{C}$ , unless other wise specified)**

Symbol	Parameter	Test conditions	Value			Unit
			Min.	Typ.	Max.	
$V_{DC}$	DC blocking voltage	$T_j=25^\circ\text{C}$	1700			V
$V_F$	Diode forward voltage	$I_F=10\text{A}$ $T_j=25^\circ\text{C}$ $I_F=10\text{A}$ $T_j=175^\circ\text{C}$		1.25 1.55	1.6	V
$I_R$	Reverse current	$V_R=1700\text{V}$ $T_j=25^\circ\text{C}$ $V_R=1700\text{V}$ $T_j=175^\circ\text{C}$		3 32	30 150	$\mu\text{A}$
$Q_C$	Total capacitive charge	$V_R=1000\text{V}$ $T_j=25^\circ\text{C}$ $Q_C = \int_0^{V_R} C(V)dV$		114		nC
C	Total capacitance	$V_R=0\text{V}$ $f=1\text{MHz}$ $V_R=800\text{V}$ $f=1\text{MHz}$ $V_R=1000\text{V}$ $f=1\text{MHz}$		2403 65 59		pF

**Thermal Characteristics**

Symbol	Parameter	Value			Unit
		Min.	Typ.	Max.	
$R_{th(jc)}$	Thermal resistance from junction to case		0.62		$^\circ\text{C/W}$

## Typical Performance

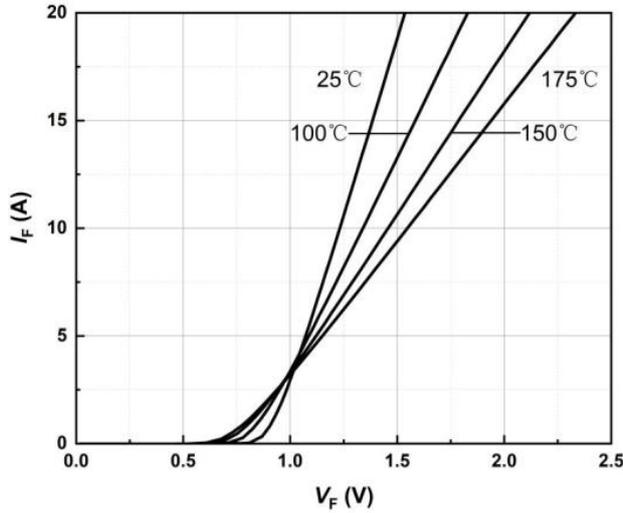


Figure 1. Typical forward characteristics

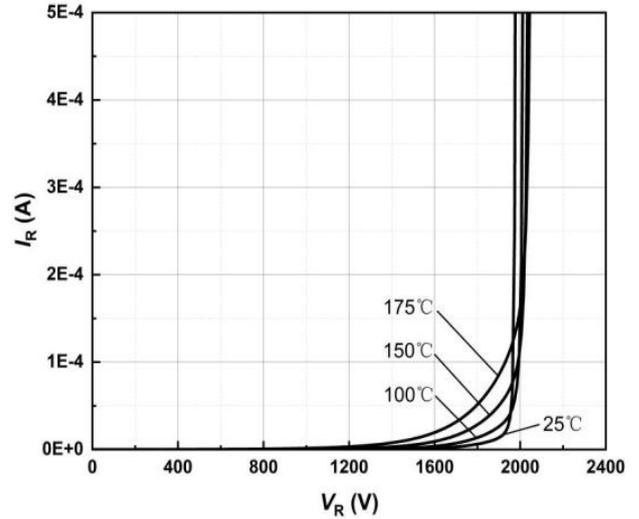


Figure 2. Typical reverse current as function of reverse voltage

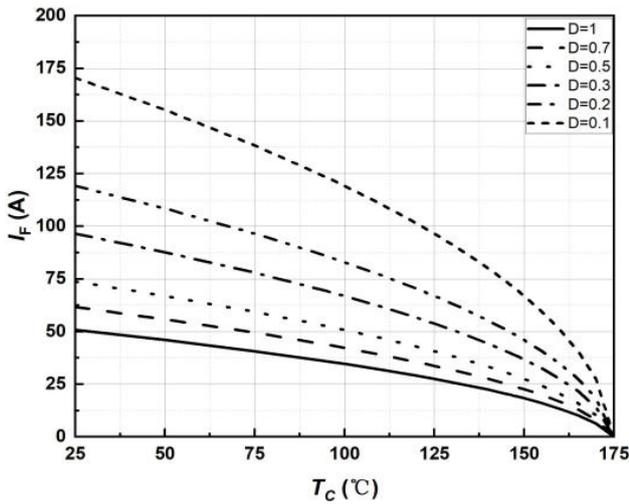


Figure 3. Diode reverse current as function of temperature, D=duty cycle

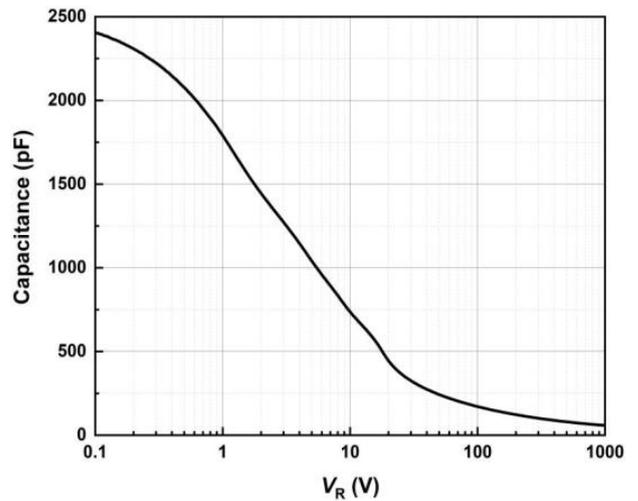


Figure 4. Typical capacitance as function of reverse voltage,  $C=f(V_R)$ ;  $T_j=25^\circ\text{C}$

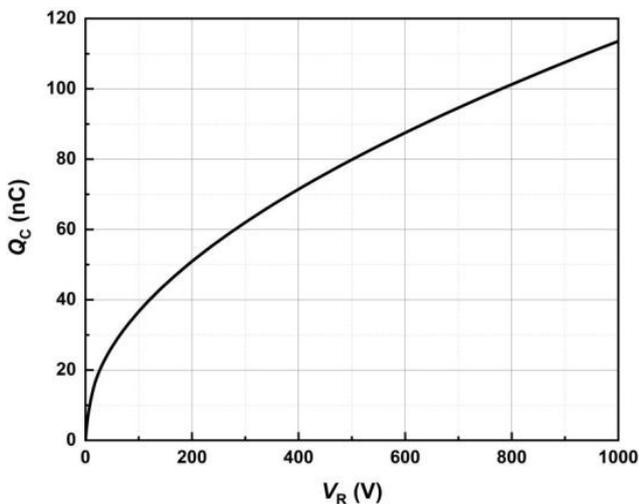


Figure 5. Typical reverse charge as function of reverse voltage

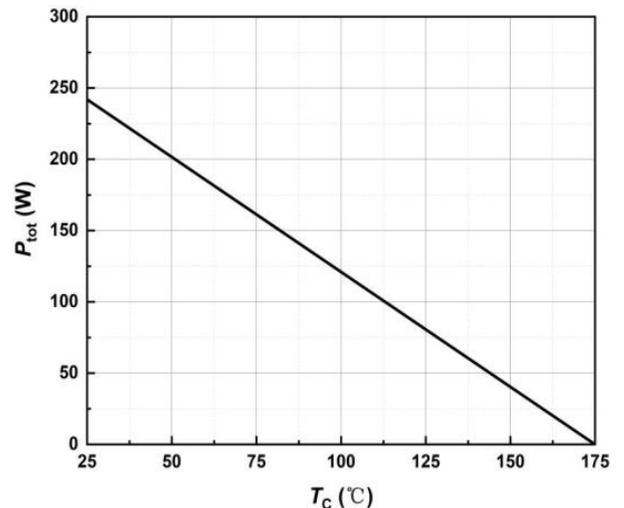


Figure 6. Power dissipation as function of case temperature

## Typical Performance

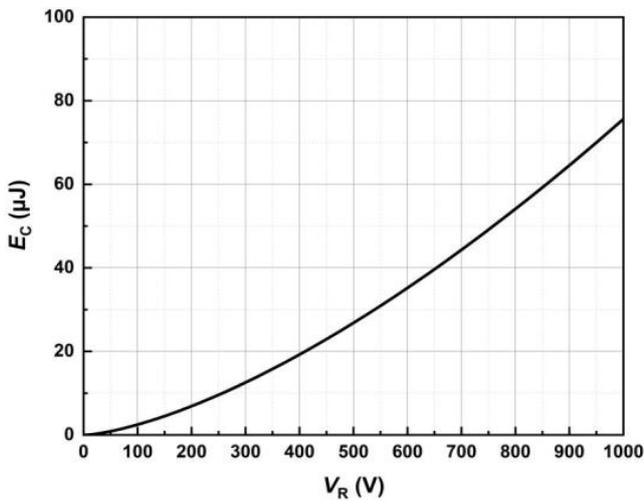


Figure 7. Capacitance stored energy

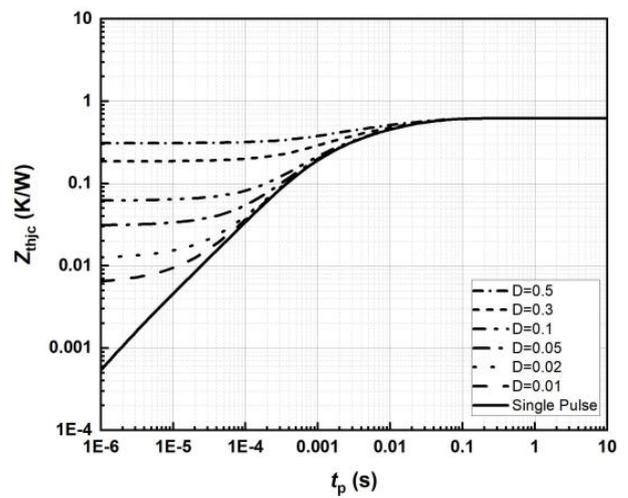


Figure 8. Max. transient thermal impedance

